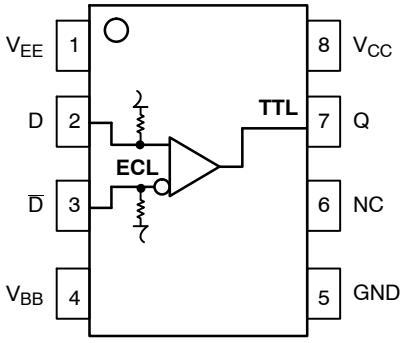


Figure 1. 8−Lead Pinout (Top View) **and Logic Diagram**

Table 1. PIN DESCRIPTION

Pin	Function
D, $\overline{D}$	ECL Differential Inputs
Q	TTL Output
V_{BB}	Reference Voltage Output
V_{CC}	Positive Supply
V_{EE}	Negative Supply
GND	Ground
NC	No Connect
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Table 2. ATTRIBUTES

Characteristics		Value	
Internal Input Pulldown Resistor		75 kΩ	
Internal Input Pullup Resistor		N/A	
ESD Protection	Human Body Model Machine Model	> 1 kV > 400 V	
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)		Pb Pkg	Pb−Free Pkg
	SOIC−8 TSSOP−8 DFN8	Level 1 Level 1 Level 1	Level 1 Level 3 Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	
Transistor Count		38 Devices	
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test			

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	Positive Power Supply	GND = 0 V	V_{EE} = −5.0 V	7	V
V_{EE}	Negative Power Supply	GND = 0 V	V_{CC} = +5.0 V	−8	V
V_{IN}	Input Voltage	GND = 0 V		0 to V_{EE}	V
I_{BB}	V_{BB} Sink/Source			± 0.5	mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	SOIC−8 SOIC−8	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	SOIC−8	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	TSSOP−8 TSSOP−8	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	TSSOP−8	41 to 44 ± 5%	°C/W
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T_{sol}	Wave Solder Pb Pb−Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
θ_{JC}	Thermal Resistance (Junction−to−Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. JEDEC standard multilayer board − 2S2P (2 signal, 2 power)

Table 4. 10ELT SERIES NECL INPUT DC CHARACTERISTICS V_{CC} = 5.0 V; V_{EE} = −5.0 V; GND = 0 V (Note 3)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{IH}	Input HIGH Voltage (Single−Ended) (Note 4)	−1230		−890	−1130		−810	−1060		−720	mV
V_{IL}	Input LOW Voltage (Single−Ended) (Note 4)	−1950		−1500	−1950		−1480	−1950		−1445	mV
V_{BB}	Output Voltage Reference	−1.43		−1.30	−1.35		−1.25	−1.31		−1.19	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Notes 4 and 5)	−2.8		0.0	−2.8		0.0	−2.8		0.0	V
I_{IH}	Input HIGH Current			255			175			175	μA
I_{IL}	Input LOW Current	0.5			0.5			0.3			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Input parameters vary 1:1 with GND. V_{EE} can vary +0.06 V to −0.5 V.
4. TTL output R_L = 500 Ω to GND
5. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with GND.

Table 5. 100ELT SERIES NECL INPUT DC CHARACTERISTICS V_{CC} = 5.0 V; V_{EE} = −5.0 V; GND = 0 V (Note 6)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V_{IH}	Input HIGH Voltage (Single−Ended) (Note 7)	−1165		−880	−1165		−880	−1165		−880	mV
V_{IL}	Input LOW Voltage (Single−Ended) (Note 7)	−1810		−1475	−1810		−1475	−1810		−1475	mV
V_{BB}	Output Voltage Reference	−1.38		−1.26	−1.38		−1.26	−1.38		−1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Notes 7 and 8)	−2.8		0.0	−2.8		0.0	−2.8		0.0	V
I_{IH}	Input HIGH Current			255			175			175	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6. Input parameters vary 1:1 with GND. V_{EE} can vary +0.8 V to −0.5 V.
7. TTL output R_L = 500 Ω to GND
8. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with GND.

Table 6. TTL OUTPUT DC CHARACTERISTICS V_{CC} = 4.5 V to 5.5 V; T_A = −40°C to +85°C

Symbol	Characteristic	Condition	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	I_{OH} = −3.0 mA	2.4			V
V_{OL}	Output LOW Voltage	I_{OL} = 24 mA			0.5	V
I_{CCH}	Power Supply Current			11	16	mA
I_{CCL}	Power Supply Current			13	18	mA
I_{EE}	Negative Power Supply Current			15	21	mA
I_{OS}	Output Short Circuit Current		−150		−60	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 7. AC CHARACTERISTICS V_{CC}= 5.0 V; V_{EE}= −5.0 V; GND= 0 V (Note 9 and Note 10)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{max}	Maximum Toggle Frequency					100					MHz
t_{PLH}	Propagation Delay @ 1.5 V	1.7		3.6	1.7		3.6	1.7		3.6	ns
t_{PHL}	Propagation Delay @ 1.5 V	2.6		4.1	2.6		4.1	2.6		4.1	ns
t_{JITTER}	Random Clock Jitter (RMS)					35					ps
t_r t_f	Output Rise/Fall Times QTTL 10% − 90%					1.9 2.3					ns
V_{PP}	Input Swing (Note 11)	200		1000	200		1000	200		1000	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

9. V_{CC} can vary ± 0.25 V.
   V_{EE} can vary +0.06 V to −0.5 V for 10ELT; V_{EE} can vary +0.8 V to −0.5 V for 100ELT.
10. R_L = 500 Ω to GND and C_L = 20 pF to GND. Refer to Figure 2.
11. V_{PP}(min) is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of ≈ 40.

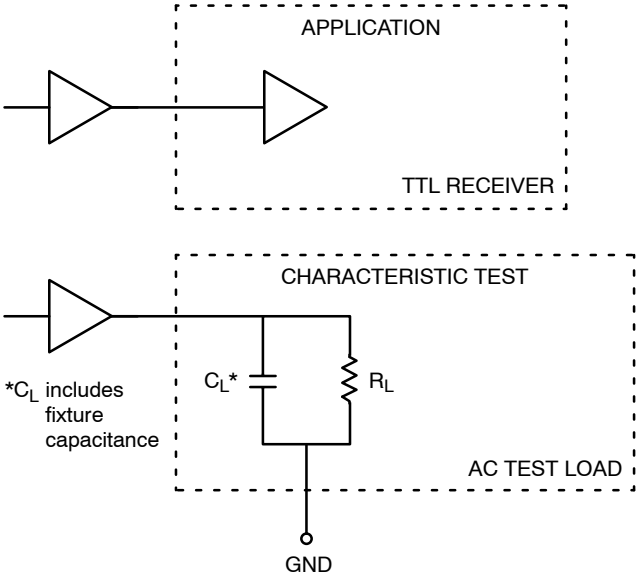


Figure 2. TTL Output Loading Used for Device Evaluation

ORDERING INFORMATION

Device	Package	Shipping†
MC10ELT25D	SOIC−8	98 Units / Rail
MC10ELT25DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC10ELT25DR2	SOIC−8	2500 / Tape & Reel
MC10ELT25DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC10ELT25DT	TSSOP−8	100 Units / Rail
MC10ELT25DTG	TSSOP−8 (Pb−Free)	100 Units / Rail
MC10ELT25DTR2	TSSOP−8	2500 / Tape & Reel
MC10ELT25DTR2G	TSSOP−8 (Pb−Free)	2500 / Tape & Reel
MC10ELT25MNR4	DFN8	1000 / Tape & Reel
MC10ELT25MNR4G	DFN8 (Pb−Free)	1000 / Tape & Reel
MC100ELT25D	SOIC−8	98 Units / Rail
MC100ELT25DG	SOIC−8 (Pb−Free)	98 Units / Rail
MC100ELT25DR2	SOIC−8	2500 / Tape & Reel
MC100ELT25DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
MC100ELT25DT	TSSOP−8	100 Units / Rail
MC100ELT25DTG	TSSOP−8 (Pb−Free)	100 Units / Rail
MC100ELT25DTR2	TSSOP−8	2500 / Tape & Reel
MC100ELT25DTR2G	TSSOP−8 (Pb−Free)	2500 / Tape & Reel
MC100ELT25MNR4	DFN8	1000 / Tape & Reel
MC100ELT25MNR4G	DFN8 (Pb−Free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

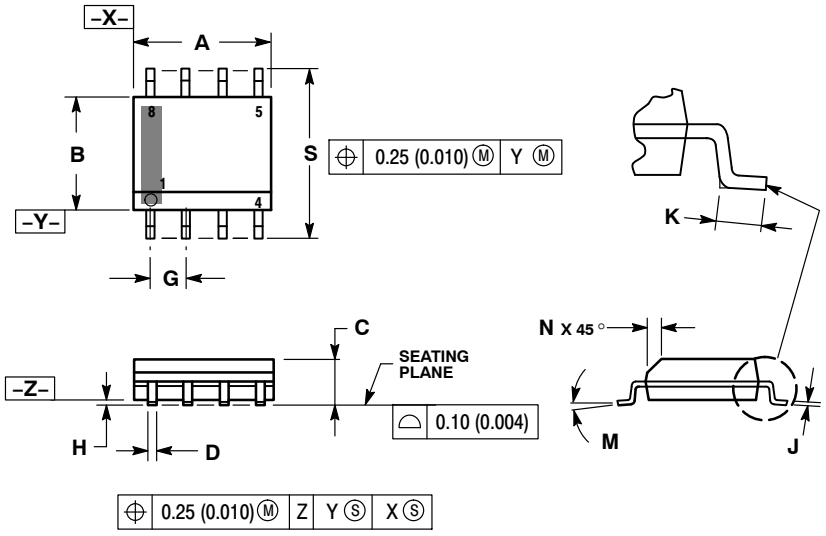
AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

AND8090/D – AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

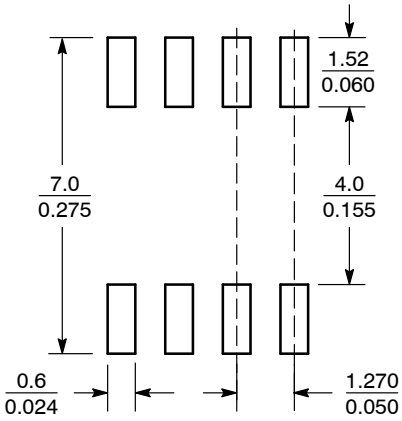
SOIC−8 NB
CASE 751−07
ISSUE AH



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

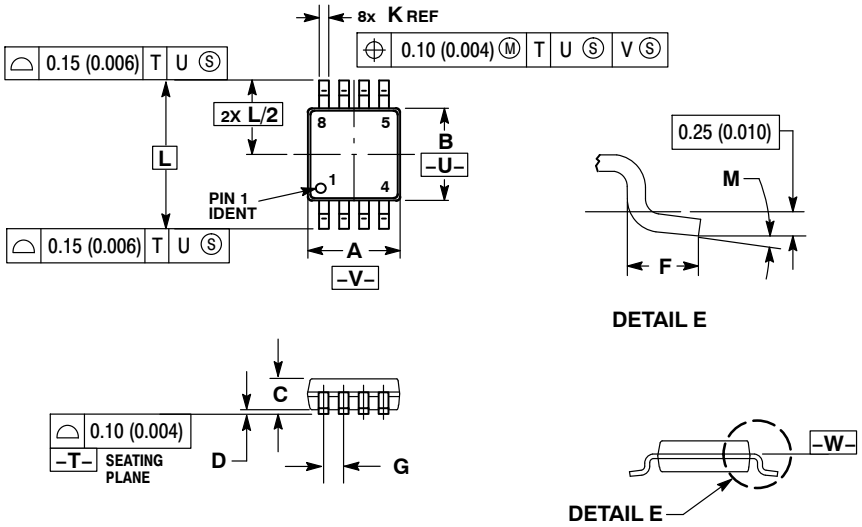


SCALE 6:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP−8
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948R−02
ISSUE A

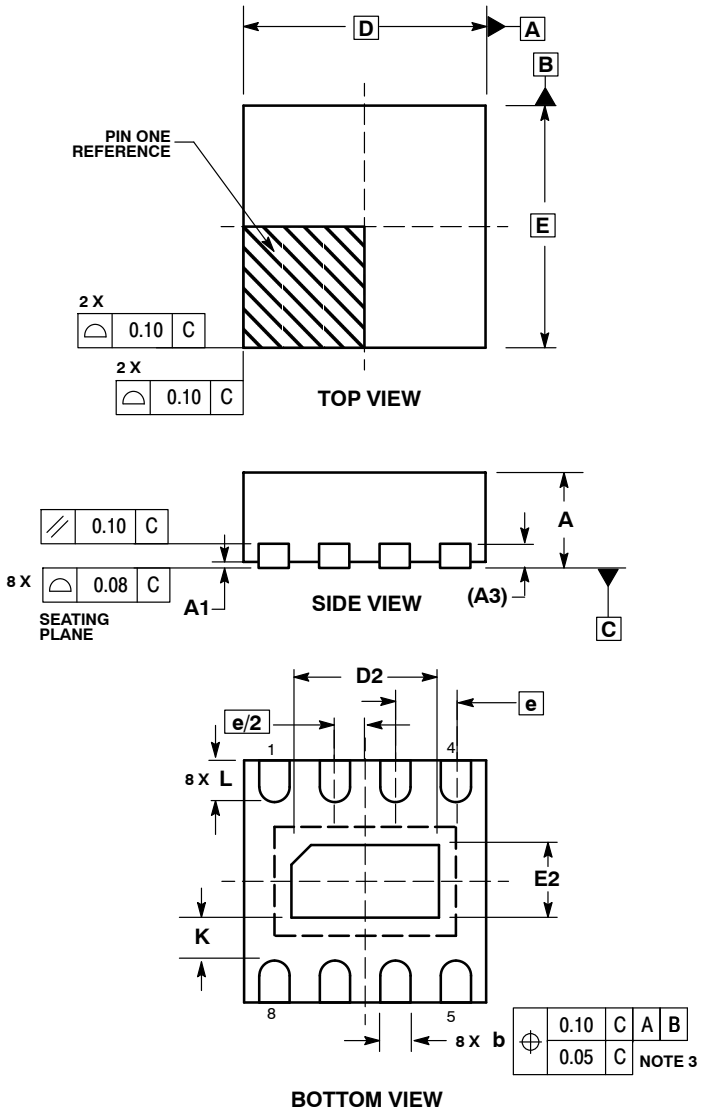


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

PACKAGE DIMENSIONS

DFN8
CASE 506AA−01
ISSUE D



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	2.00 BSC	
D2	1.10	1.30
E	2.00 BSC	
E2	0.70	0.90
e	0.50 BSC	
K	0.20	−−−
L	0.25	0.35

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MC10ELT25/D